L Number	Hits	Search Text	DB	Time stamp
1	728157	mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:14
2	396578	photolithograph$6 photoresist photosensitive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:15
3	318129	spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:15
5	30639	349$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:15
4	12	mold near10 (photolithograph$6 photoresist photosensitive) near10 spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:18
6	58	mold same (photolithograph$6 photoresist photosensitive) same spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:18
7	4	349$.ccls. and (mold same (photolithograph$6 photoresist photosensitive) same spacer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:19
8	46	(mold same (photolithograph$6 photoresist photosensitive) same spacer) not (mold near10 (photolithograph$6 photoresist photosensitive) near10 spacer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 13:19

L Number	Hits	Search Text	DB	Time stamp
1	1383	(349/155,156).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:08
2	1091	(264/61,129,272.1).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:09
3	2681	438/624.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:09
4	1432	445/24.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:09
5	513	(216/25,33).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:09
6	1551	(427/77,105,106,133).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:09
7	6669	(primary positive) near5 mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:10
8	119676	photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:10
9	343373	spacer (dielectric adj (sturcture film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:11
11	0	(spacer (dielectric adj (sturcture film))) same (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:12
12	0	((349/155,156).ccls.) and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:12
13	0	((264/61,129,272.1).ccls.) and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:12
14	0	438/624.ccls. and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:12
15	0	445/24.ccls. and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:12

17	0	((427/77,105,106,133).ccls.) and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:12
16	1	((216/25,33).ccls.) and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:12
18	2	(spacer (dielectric adj (sturcture film))) and (((primary positive) near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:13
10	31	((primary positive) near5 mold) same photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:16
19	85551	photolithograph$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:16
20	6	((primary positive) near5 mold) near10 photolithograph$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:17
21	0	((primary positive) near5 mold) same photolithograph$5 same (spacer (dielectric adj (sturcture film)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:18
22	9	((primary positive) near5 mold) same photolithograph$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:18
23	3	(((primary positive) near5 mold) same photolithograph$5) not (((primary positive) near5 mold) near10 photolithograph$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:18
24	1091	264/129.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:19
25	14	((primary positive) near5 mold) and 264/129.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:20
26	0	((349/155,156).ccls.) and ((primary positive) near5 mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:20
27	48	(spacer (dielectric adj (sturcture film))) same ((primary positive) near5 mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 11:20